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Bjorndahl, W.D.;

Aerospace Conference, 1997. Proceedings., IEEE , Volume: 4 , 1-8 Feb. 1997
 Pages:277 - 283 vol.4

[\[Abstract\]](#) [\[PDF Full-Text \(504 KB\)\]](#) **IEEE CNF**

2 An ac impedance in situ methodology for assessing high reliability performance of plastic encapsulated microelectronics in harsh environments

Lumsden, J.; Kuo, J.; Pollock, G.;

Electronic Components and Technology Conference, 2002. Proceedings. 52nd , 28-31 May 2002
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3 Critical issues in thin layer acoustic image interpretation and metrology for microelectronics

Canumalla, S.;

Electronic Components and Technology Conference, 2002. Proceedings. 52nd , 28-31 May 2002
 Pages:205 - 218

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4 The use of time domain spectroscopy as a diagnostic tool for rotating machine windings

David, E.; Lamarre, L.; Nguyen, D.N.;

Electrical Insulation, 2002. Conference Record of the 2002 IEEE International Symposium on , 7-10 April 2002
 Pages:506 - 510